



Product Change Notification

Change Notification #: 118989-00
Change Title: Select Boxed Intel® Core™ i9-12900F Processors,
Boxed Intel® Core™ i9-12900 Processors,
PCN 118989-00, Product Design,
CPU Mounting Hardware Update
Date of Publication: March 28, 2022

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material	April 28, 2022
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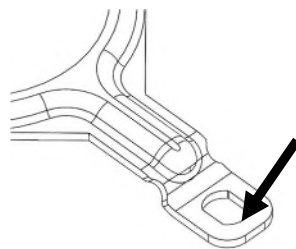
Description of Change to the Customer:

Intel will start transitioning the mounting hardware for the stock cooler included in the Boxed Intel Core i9-12900/F Processors to a new design with refined features.

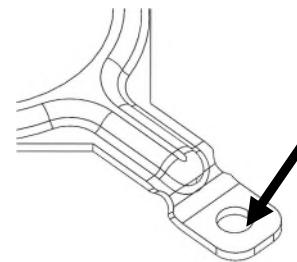
Summary of changes:

- Cooler mounting legs: Changed profile of through-hole to remove unnecessary fastener adjustability feature.

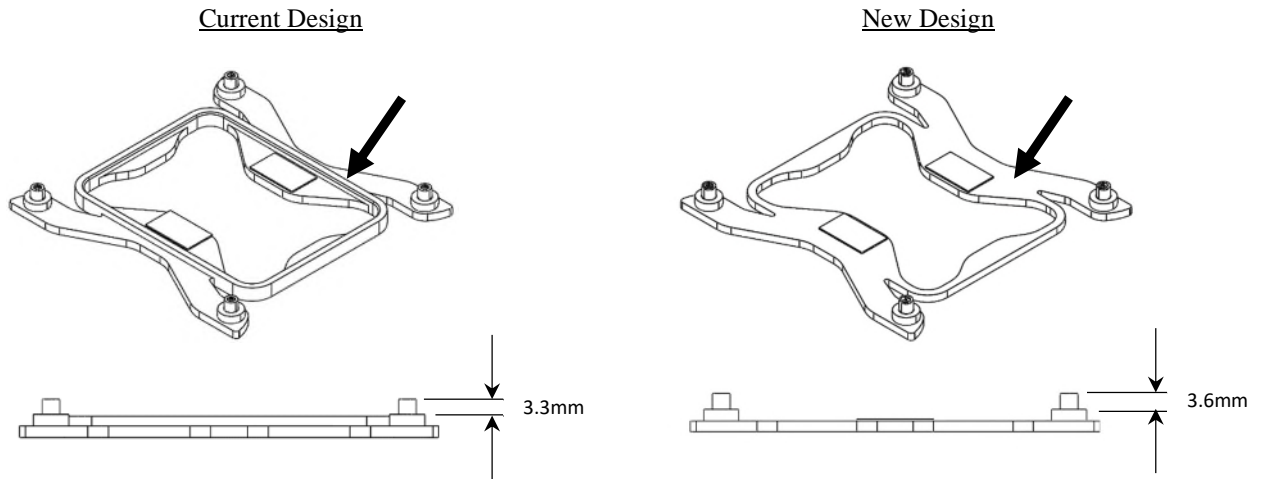
Current Design



New Design



- Cooler mounting backplate: Removed unnecessary rib feature surrounding CPU socket backplate and increased standoff height for a small reduction in heatsink load.



Customer Impact of Change and Recommended Action:

Intel anticipates no change in useability or performance of the stock cooler mounting hardware.

Products Affected/Intel Ordering Codes:

Marketing Name	Stepping	MM#	Product Code	Spec Code	Platform
Boxed Intel® Core™ i9-12900 Processor	C0	99ARGF	BX8071512900	S RL4K	DESKTOP
Boxed Intel® Core™ i9-12900F Processor	C0	99ARGM	BX8071512900F	S RL4L	DESKTOP
Boxed Intel® Core™ i9-12900 Processor	C0	99ARGR	BXC8071512900	S RL4K	DESKTOP
Boxed Intel® Core™ i9-12900F Processor	C0	99ARGX	BXC8071512900F	S RL4L	DESKTOP

PCN Revision History:

Date of Revision:

March 28, 2022

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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